

10/585461**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**Applicants: J. TAKETATSU, et al. **1AP20 Rec'd PCT/PTO 07 JUL 2006**

Serial No.: NEW

Filed: JULY 7, 2006

For: CIRCUIT CONNECTION MATERIAL, FILM-SHAPED CIRCUIT
CONNECTION MATERIAL USING THE SAME, CIRCUIT
MEMBER CONNECTION STRUCTURE, AND
MANUFACTURING METHOD THEREOF**PRELIMINARY AMENDMENT****Mail Stop: NEW APPS**
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

July 7, 2006

Sir:

Please amend the above-identified application, prior to calculation of the filing fee, as listed in the following, and as set forth on the following pages:

AMENDMENTS TO THE CLAIMS; and

REMARKS are included following the amendments.